

Material Declaration Report

Package Type:	TSSOP 64L (6.1mm)
Pericom Package Code:	A64(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	263.851
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	12/2/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	151.000	OSE	Silica Fused	60676-86-0	89.800	135.5980
			Epoxy Resin	Proprietary	5.000	7.5500
			Phenolic Resin	Proprietary	4.000	6.0400
			Others	Proprietary	1.000	1.5100
			Carbon Black	1333-86-4	0.200	0.3020
LEADFRAME	103.000		Copper (Cu)	7440-50-8	94.900	97.7470
			Nickel (Ni)	7440-02-0	3.200	3.2960
			Silicon (Si)	7440-21-3	0.720	0.7416
			Magnesium (Mg)	7439-95-4	0.180	0.1854
			Silver(Ag)	7440-22-4	1.000	1.0300
SILICON DIE	2.701		Silicon (Si)	7440-21-3	99.192	2.6792
			Non-hazardous Metal	Proprietary	0.808	0.0218
DIE ATTACH EPOXY	1.050		Silver	7440-22-4	76.000	0.7980
			Acrylic Resin	Proprietary	8.000	0.0840
			Acrylate	Proprietary	5.500	0.0578
			Polybutadiene derivative	Proprietary	5.500	0.0578
			Epoxy resin	Proprietary	2.500	0.0263
			Additive	Proprietary	1.000	0.0105
			Butadiene copolymer	Proprietary	1.000	0.0105
			Peroxide	Proprietary	0.500	0.0053
GOLD WIRE	1.600		Gold(Au)	7440-57-5	99.990	1.5998
			Impurities	-	0.010	0.0002
SOLDER PLATING	4.500		Tin (Sn)	7440-31-5	99.990	4.4996
			Impurities	-	0.010	0.0005

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table> <p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													